



## Device Material Content

5555 NE Moore Ct. Hillsboro OR 97124 <a href="mailto:custrec@lsc.com">custrec@lsc.com</a>  January, 2018				<b>Package: 24 QFNS</b> <b>Total Device Weight 0.042 Grams</b>			<b>Package Code:</b> <div style="border: 1px solid black; padding: 2px; display: inline-block;">SN24</div>		Assembly: Unisem Size (mm): 4 x 4 x 0.9 Lead pitch (mm): 0.5 MSL: 1 Reflow max (°C): 260		
				<b>Products:</b> <div style="border: 1px solid black; padding: 2px; display: inline-block;">PAC-POWR</div>							
	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:			
Die	5.55%	0.0023	5.55%	0.0023	Silicon chip	7440-21-3	100.00%	Die size: 2.00 x 2.00 mm			
Mold Compound	56.46%	0.0237	49.69%	0.0209	Silica Fused	60676-86-0	88.00%	Mold Compound: Sumitomo EME-G770			
			2.82%	0.0012	Epoxy Resins	-	5.00%				
			2.82%	0.0012	Phenol Resins	-	5.00%				
			0.99%	0.0004	Metal Hydroxide	-	1.75%				
			0.14%	0.0001	Carbon Black	1333-86-4	0.25%				
D/A Epoxy	0.97%	0.0004	0.73%	0.00030	Silver	7440-22-4	75.00%	Die attach: Sumitomo CRM1066 series			
			0.10%	0.00004	Epoxy Resin A	9003-36-5	10.00%				
			0.15%	0.00006	Esters & resins	-	15.00%				
Wire	0.67%	0.0003	0.67%	0.0003	Gold (Au)	7440-57-5	100.00%	0.8 mil wire diameter; 1 wire for each package lead			
Plating	2.10%	0.0009	2.10%	0.0009	Tin (Sn)	7440-31-5	100.00%	Plating is 100% Matte Sn; thickness is >10.2µm			
Leadframe	34.25%	0.0144	33.39%	0.0140	Copper	7440-50-8	97.50%	A194			
			0.75%	0.0003	Iron	7439-89-6	2.19%				
			0.03%	0.0000	Phosphorus	7723-14-0	0.08%				
			0.04%	0.0000	Zinc	7440-66-6	0.12%				
			0.04%	0.0000	Silver	7440-22-4	0.12%				

**Notes:**  
 The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.  
 Constituent substances and proportions in epoxy materials are before curing.  
 The information provided above is representative of the package as of the date listed, and is subject to change at any time.  
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